12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN20260202000.1
Qualification of additional Assembly sites for select SOT-23 devices
Change Notification / Sample Request

Date: February 02, 2026
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20260202000.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records**,** you have recently purchased these devices**.** The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
ATL431LIBIDBZR	ATL431LIBIDBZR
TPD4S009DBVRG4	NULL
TPS2068EDBVR	NULL
OPA348AIDBVT	NULL
TL432LIAQDBZR	TL432LIAQDBZR
TLV803RDBZT	TLV803RDBZT
TPS2000EDBVR	NULL
TLV803SDBZT	TLV803SDBZT
TS5A63157DBVR	TS5A63157DBVR
TS5A1066DBVR	TS5A1066DBVR
TPD4S009DBVR	NULL
TS5A3167DBVR	NULL
OPA348AIDBVR	NULL
TLV803MDBZR	TLV803MDBZR
TPS22929DDBVR	TPS22929DDBVR

Technical details of this Product Change follow on the next page(s).

PCN Number:	PCN#20260202000.1	**PCN Date:**	February 02, 2026
Title:	Qualification of additional Assembly sites for select SOT-23 devices		
Customer Contact:	Change Management Team	**Dept:**	Quality Services
Proposed 1st Ship Date:	May 03, 2026	**Sample requests accepted until:**	April 03, 2026*

***Sample requests received after April 03, 2026 will not be supported.**

Change Type:

☒	Assembly Site	☐	Design	☐	Wafer Bump Material
☒	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Material
☒	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

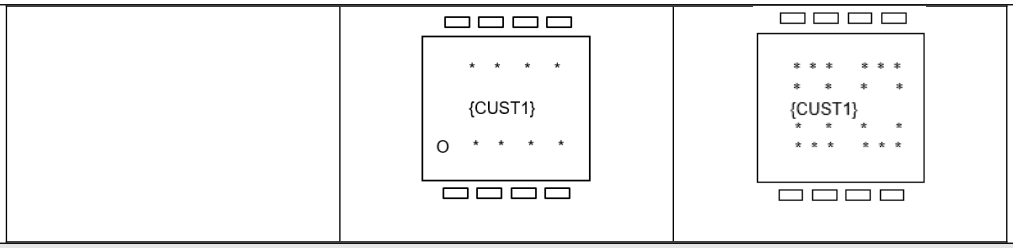
Description of Change:

Texas Instruments Incorporated is announcing the qualification of additional Assembly sites for devices listed below in the product affected section. Construction information and all assembly sites are as follows:

SOT-23 Build sites	
Assembly Sites	CDAT, HFTF, HNA, TFME, PHI, TIEMA
Mount Compound	4207123
	4229877
	4226215
	SID#A-09
	SID#A-03
	SID#A-21
	SID#400180
	SID#A-20
	8080598
Mold Compound	4222198
	SID#R-17
	SID#450042
	SID#450413
	SID# R-04
	SID#450207
	8095181
Lead frame Finish	NiPdAu, Matte Sn
Bond Wire (mil)	Au, Cu (0.8mil, 1.0mil, 1.3mil)

Device marking:

	Current	**Additional**
Marking differences	Binary code	Secondary Binary code



Reason for Change:

Continuity of Supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
CDAT	CDA	CHN	Chengdu
HFTF	HFT	CHN	Hefei
HNA	HNT	THA	Ayutthaya
TFME	NFM	CHN	Chongchuan
PHI	PHI	PHL	Baguio city
TIEMA	CU6	MYS	Melaka

Sample product shipping label (not actual product label)

Product Affected:

ATL431LIBIDBZR	TLV803MDBZR	TPS22929DDBVT
ATL431LIBQDBZR	TLV803RDBZT	TPD4S009DBVR
OPA348AIDBVR	TLV803SDBZT	TPD4S009DBVRG4*
OPA348AIDBVRG4*	TLV853MDBZR	TS5A1066DBVR
OPA348AIDBVT	TPS2000EDBVR	TS5A3167DBVR
OPA348AIDBVTG4*	TPS2068EDBVR	TS5A63157DBVR
TL432LIAQDBZR	TPS22929DDBVR	

Note: *- G4 material will use NiPdAu lead finish

SOT-23 Qualification Report

Data Displayed as: Number of lots / Total sample size / Total failed

	Stress Test	Duration	PHI TPS76933DBV	CDAT TLV9061IDBV
TC	Temperature Cycling -65/150C	500 Cycles	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0	3/231/0
UHAST	Unbiased HAST, 130C/85%RH	96 hours	-	3/231/0
AC	Autoclave 121C	96 hours	3/231/0	-
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	3/66/0
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	TFME SN74AHC1G14DBV	HNA INA293A1IDBV
TC	Temperature Cycling -65/150C	500 Cycles	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0	3/231/0
UHAST	Unbiased HAST, 130C/85%RH	96 hours	-	3/231/0
AC	Autoclave 121C	96 hours	3/231/0	-
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	3/66/0 (SN74LVC1GU04DBV)
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	TIEMA DAC121S101CIMK	HFTAT TLV70333DBV
TC	Temperature Cycling -65/150C	500 Cycles	-	3/231/0
TC	Temperature Cycling -55/150C	1000 Cycles	3/231/0	-
HAST	Biased HAST 130C/85%RH	96 hours	-	3/231/0
THB	Temperature Humidity Bias, 85C/85%RH	1000 hours	3/231/0	-
HTSL	High Temp. Storage Bake 150C	1000 hours	3/231/0	-
HTSL	High Temp. Storage Bake 170C	420 hours	-	3/231/0
UHAST	Unbiased HAST, 130C/85%RH	96 hours	-	3/231/0
AC	Autoclave 121C	96 hours	3/231/0	-
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0 (LM2660MM/NOPB)	3/66/0 (TLV74333PDBV)
MQ	Manufacturability	-	Pass	Pass

All qualification devices in the tables are qualified at L1-260C MSL rating.

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, and HTSL, as applicable
- The following are equivalent HTSL options based on activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status: Qualified Pb-Free (SMT) and Green

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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